Nch 100V 295A Power MOSFET

V_{DSS}	100V
R _{DS(on)} (Max.)	2.00mΩ
I _D	±295A
P_D	375W

● Features

- 1) Low on resistance
- 2) High power package(TOLL-9LSATAC)
- 3) Pb-free plating; RoHS compliant
- 4) Halogen Free
- 5) 100% Rg and UIS tested

Application

Switching

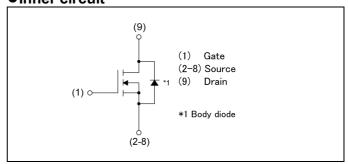
Motor drives

DC/DC converter

Outline



•Inner circuit



Packaging specifications

- 1 40114	Jing specifications	
	Packing	Embossed Tape
	Reel size (mm)	330
Туре	Tape width (mm)	24
	Quantity (pcs)	2000
	Taping code	TRDC
	Marking	RJ2P17BBH

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified)

Para	Symbol	Value	Unit	
Drain - Source voltage	V _{DSS}	100	V	
Captinuous drain surrent	Silicon limit (V _{GS} =10V)	I _D *1	±295	Α
Continuous drain current	$T_c = 25^{\circ}C (V_{GS} = 10V)$	I _D *2	±175	Α
Pulsed drain current		I _{DP} *3	±1180	Α
Gate - Source voltage		V_{GSS}	±20	V
Avalanche current, single pulse		l _{AS} *4	110	Α
Avalanche energy, single pulse		E _{AS} *4	605	mJ
Power dissipation		P _D *2	375	W
Junction temperature		T _j	175	°C
Operating junction and stor	age temperature range	T _{stg}	-55 to +175	°C

●Thermal resistance

Parameter	Symbol	Values			l læit
		Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R _{thJC} *2	-	-	0.4	°C/W

● Electrical characteristics (T_a = 25°C)

Davamatav	Cymah ol	Conditions	Values			l limit
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit
Drain - Source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 1mA	100	-	-	V
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I _D = 1mA referenced to 25°C	-	62.3	-	mV/°C
Zero gate voltage drain current	I_{DSS} $V_{DS} = 100V, V_{GS} = 0V$		-	-	1	μA
Gate - Source leakage current	I _{GSS}	I_{GSS} $V_{GS} = \pm 20V, V_{DS} = 0V$		-	±500	nA
Gate threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 1mA$	2.0	-	4.0	V
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_{j}}$	I _D = 1mA referenced to 25°C	-	-4.5	-	mV/°C
Static drain - source	D *5	V _{GS} = 10V, I _D = 100A	-	1.60	2.00	O
on - state resistance	R _{DS(on)} *5	V _{GS} = 6V, I _D = 85A	-	1.93	2.80	mΩ
Gate resistance	R _G -		-	2.6	-	Ω
Forward Transfer Admittance	Y _{fs} *5	V _{DS} = 5V, I _D = 50A	65	-	-	S

^{*1} Limited by silicon chip capability.

^{*2} T_c=25°C, Limited only by maximum temperature allowed.

^{*3} Pw \leq 10µs, Duty cycle \leq 1%.

^{*4} L=0.1mH, Design value

^{*5} Pulsed

● Electrical characteristics (T_a = 25°C)

Dorameter	Cumb of	Conditions		Unit			
Parameter	Symbol Conditions		Min.	Тур.	Max.	Urill	
Input capacitance	C _{iss}	V _{GS} = 0V	-	9500	-		
Output capacitance	C _{oss}	V _{DS} = 50V	-	1700	-	pF	
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	200	-		
Turn - on delay time	t _{d(on)} *5	$V_{DD} \simeq 50V, V_{GS} = 10V$	1	65	ı		
Rise time	t r*5	I _D = 50A	1	80	ı	no	
Turn - off delay time	t _{d(off)} *5	$R_L \simeq 1\Omega$	-	200	-	ns	
Fall time	t _f *5	$R_G = 10\Omega$	-	115	-		

• Gate charge characteristics $(T_a = 25^{\circ}C)$

Daramatar	Cymahal	Conditions		Values			l lait		
Parameter	Symbol			Min.	Тур.	Max.	Unit		
Total gate aborge	O *5		V _{GS} = 10V	-	145	-			
Total gate charge	Q_g^{*5}	\mathbf{Q}_{g}^{s}	Q_g	V _{DD} ≃ 50V		-	92	-	~C
Gate - Source charge	Q _{gs} *5	I _D = 50A	V _{GS} = 6V	-	36	-	nC		
Gate - Drain charge	Q _{gd} *5			-	33	-			

● Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
	Symbol	I Conditions		Тур.	Max.	Offic
Continuous forward current	I _S *2		-	-	175	Α
Pulse forward current	I _{SP} *3	-	-	-	1180	Α
Forward voltage	V _{SD} *5	V _{GS} = 0V, I _S = 100A	-	-	1.2	V
Reverse recovery time	t _{rr} *5	I _S = 50A, V _{GS} =0V	-	110	-	ns
Reverse recovery charge	Q _{rr} *5	di/dt = 100A/μs	-	400	-	nC

• Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

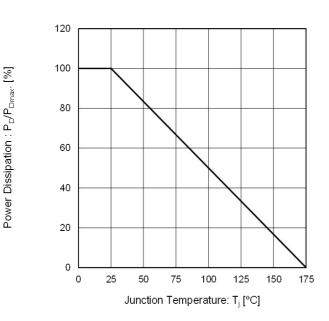
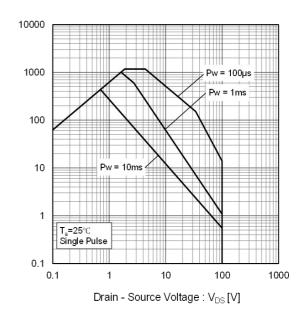


Fig.2 Maximum Safe Operating Area



Drain Current : I_D [A]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

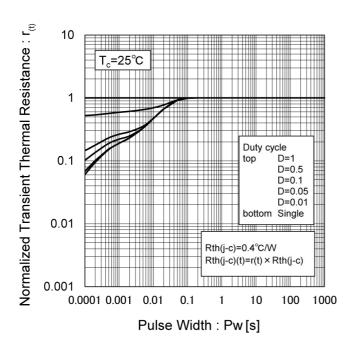
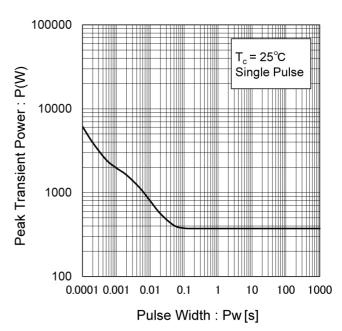


Fig.4 Single Pulse Maximum Power Dissipation



Drain Current : I_D [A]

• Electrical characteristic curves

Fig.5 Typical Output Characteristics(I)

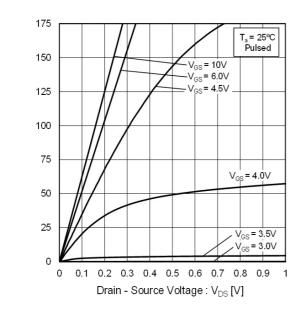


Fig.6 Typical Output Characteristics(II)

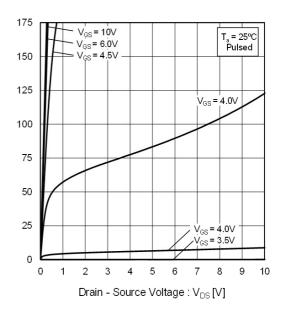


Fig.7 Normalized Breakdown Voltage vs. Junction Temperature

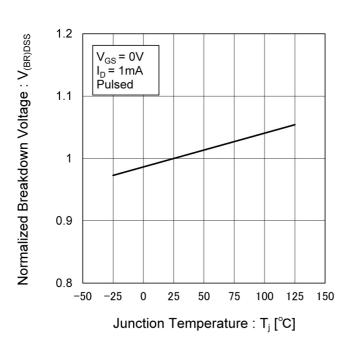
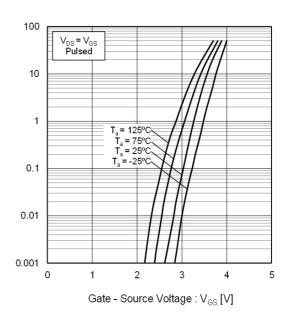


Fig.8 Typical Transfer Characteristics



Drain Current : I_D [A]

Drain Current : I_D [A]

Gate Threshold Voltage: V_{GS(th)} [V]

• Electrical characteristic curves

Fig.9 Gate Threshold Voltage vs.
Junction Temperature

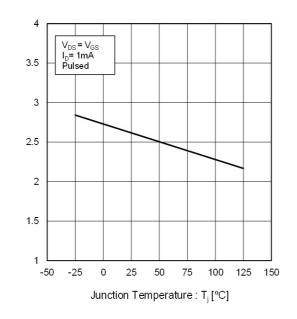


Fig.10 Forward Transfer Admittance vs.
Drain Current

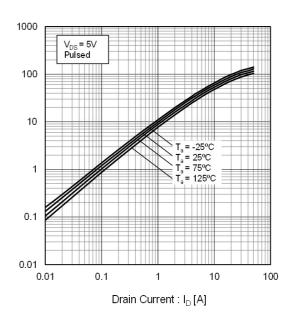


Fig.11 Drain Current Derating Curve

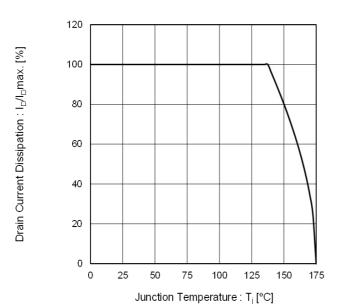
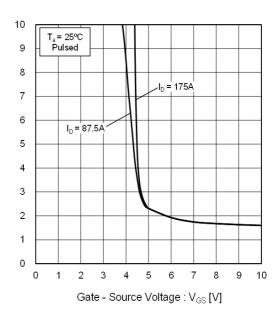


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage



Static Drain - Source On-State Resistance : $R_{\text{DS}(on)}\left[\text{m}\Omega\right]$

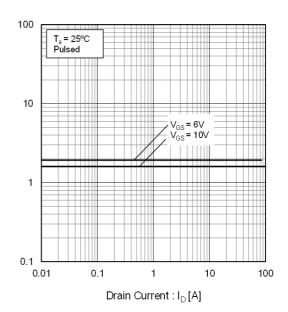
Forward Transfer Admittance : Y_{fs} [S]

• Electrical characteristic curves

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

V_{GS}= 10V Pulsed Static Drain - Source On-State Resistance 3 : R_{DS(on)} [mΩ] 2 I_D = 100A 1 0 -50 -25 50 75 100 125 150 0 25 Junction Temperature : T_i [°C]

Fig.14 Static Drain - Source On - State
Resistance vs. Drain Current (I)



Static Drain - Source On-State Resistance : $R_{\mathrm{DS}(on)}\left[m\Omega\right]$

Static Drain - Source On-State Resistance : $R_{\mathrm{DS}(\text{on})}\left[m\Omega\right]$

Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

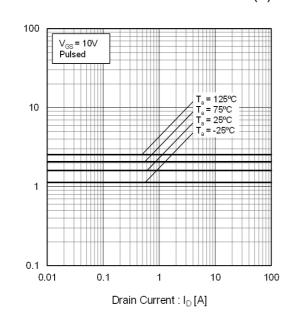
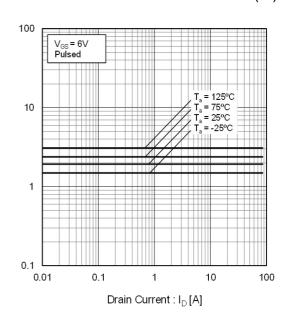


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)



Static Drain - Source On-State Resistance

 $:R_{DS(on)}[m\Omega]$

• Electrical characteristic curves

Fig.17 Typical Capacitances vs.

Drain - Source Voltage

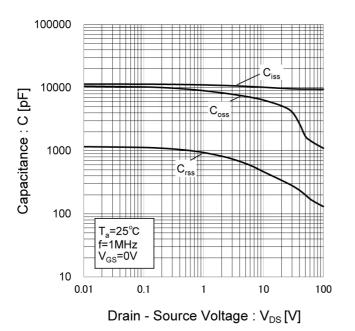


Fig.18 Switching Characteristics

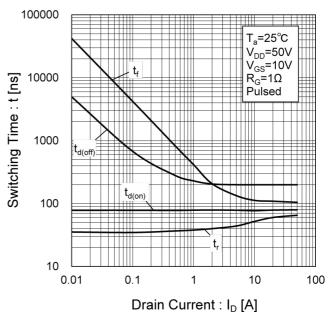


Fig.19 Typical Gate Charge

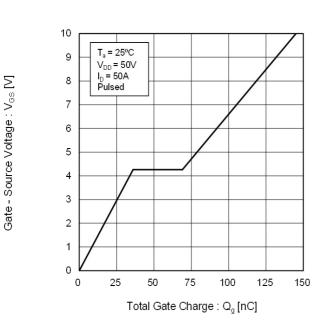
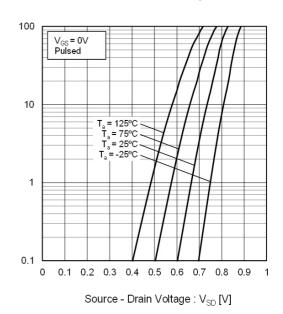


Fig.20 Source Current vs.

Source Drain Voltage



Source Current : I_s [A]

Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

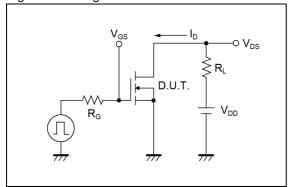


Fig.1-2 Switching Waveforms

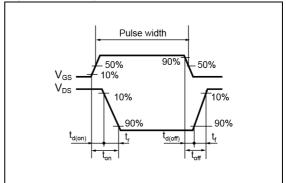


Fig.2-1 Gate Charge Measurement Circuit

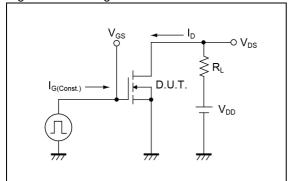
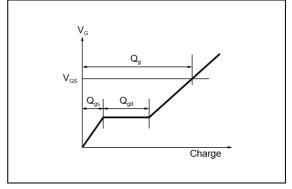
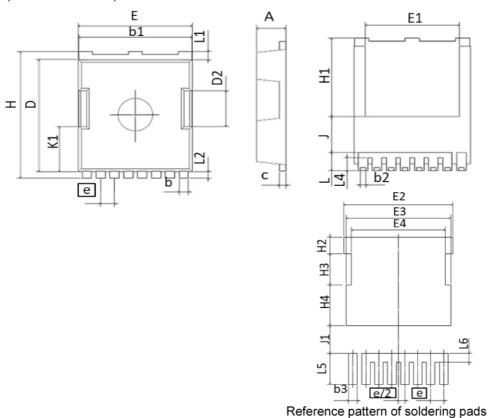


Fig.2-2 Gate Charge Waveform



Dimensions

TOLL MO-299 (TOLL-9LSATAC)



DIM	Milim	neters	Inc	hes	
D	Min.	Max.	Min.	Max.	
Α	2.20	2.40	0.087	0.094	
b	0.65	0.95	0.026	0.037	
b1	9.65	9.95	0.380	0.392	
b2	0.38	0.54	0.015	0.021	
С	0.40	0.60	0.016	0.024	
D	10.28	10.58	0.405	0.417	
D2	3.10	3.50	0.122	0.138	
E	9.70	10.10	0.382	0.398	
E1	7.90	8.30	0.311	0.327	
е	1.	20	0.0	047	
Н	11.48	11.88	0.452	0.468	
H1	6.75	7.15	0.266	0.281	
J	3.00	3.30	0.118	0.130	
K1	3.98	4.38	0.157	0.172	
L	1.40	1.80	0.055	0.071	
L1	0.60	0.80	0.024	0.03	
L2	0.50	0.70	0.020	0.028	
L4	1.00	1.30	0.039	0.05	
DIM	Millim	neters	Inc	hes	
Diiii		om.		om.	
b3	0.80			031	
E2	10.10		0.398		
E3		9.70		382	
E4	8.	8.70		0.343	
H2	1.	.50	0.059		
Н3	2.	2.80		110	
H4		3.70		146	
J1	2.	2.50		98	
L5		80	0.1	110	
L6	0	80		031	

Dimension in mm/inches



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JAPAN	USA	EU	CHINA
CLASSⅢ	CL ACCIII	CLASS II b	CI VCCIII
CLASSIV	CLASSII	CLASSⅢ	CLASSⅢ

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 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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